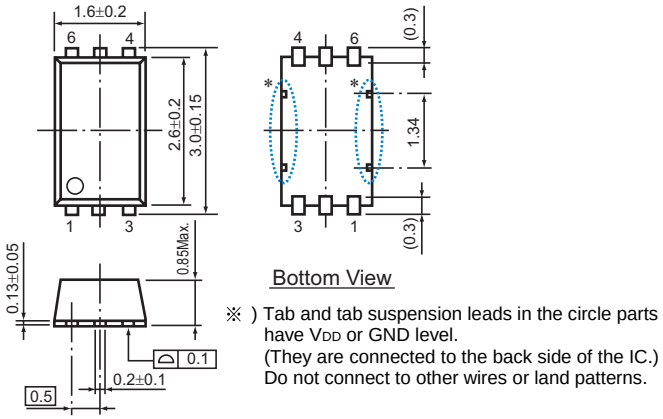
- **SON-6**

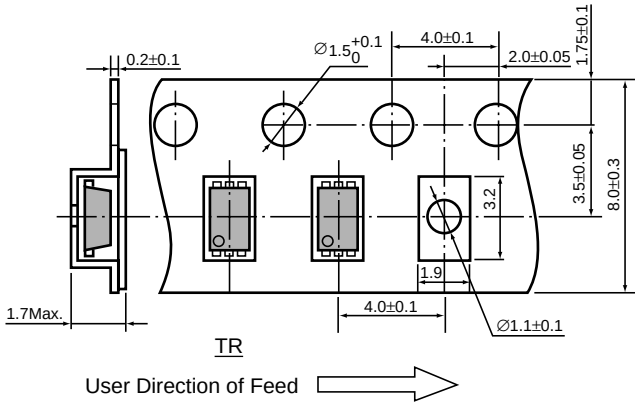
Unit: mm

PACKAGE DIMENSIONS



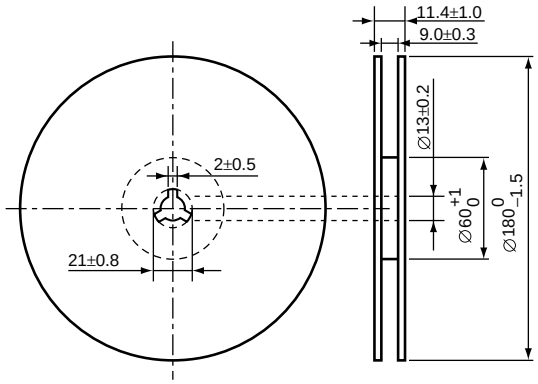
※) Tab and tab suspension leads in the circle parts have V_{DD} or GND level.
(They are connected to the back side of the IC.)
Do not connect to other wires or land patterns.

TAPING SPECIFICATION



TAPING REEL DIMENSIONS REUSE REEL (EIAJ-RRM-08Bc)

(1reel=3,000pcs)



POWER DISSIPATION (SON-6)

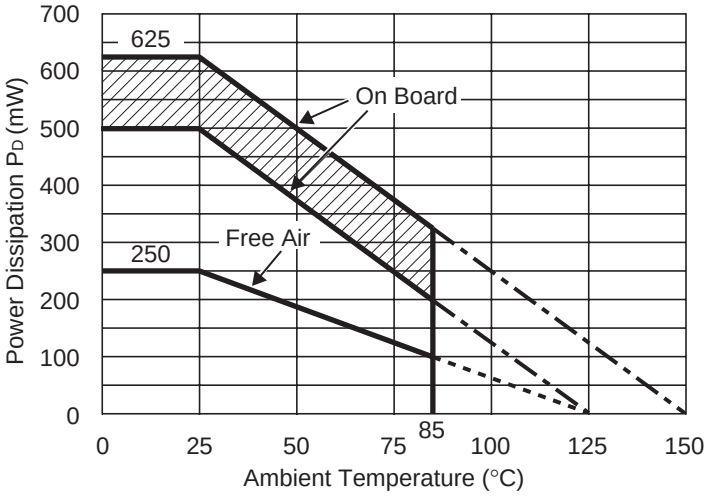
This specification is at mounted on board. Power Dissipation (P_D) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

Measurement Conditions

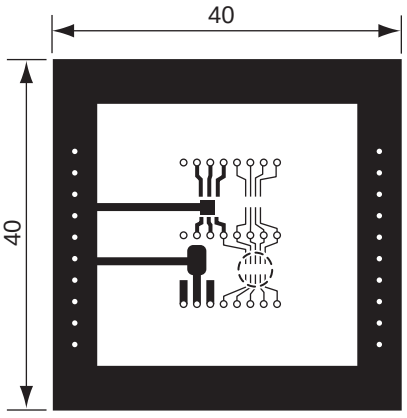
	Standard Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (Double sided)
Board Dimensions	40mm × 40mm × 1.6mm
Copper Ratio	Top side : Approx. 50% , Back side : Approx. 50%
Through-holes	ϕ0.5mm × 44pcs

Measurement Results (Topt=25°C,Tjmax=125°C)

	Standard Land Pattern	Free Air
Power Dissipation	500mW	250mW
Thermal Resistance	θja=(125−25°C)/0.5W=200°C/W	−



Power Dissipation



Measurement Board Pattern

IC Mount Area (Unit: mm)

The above graph shows the Power Dissipation of the package based on Tjmax=125°C and Tjmax=150°C.

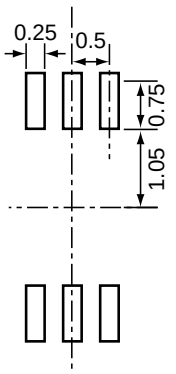
Operating the IC in the shaded area in the graph might have an influence it's lifetime.

Operating time must be within the time limit described in the table below, in case of operating in the shaded area.

Product Name	Operating time	Estimated years*
R1163D R1131Dxx1	9,000hrs	6years

*The volume is calculated on the supposition that operating four hours/day.

RECOMMENDED LAND PATTERN



(Unit: mm)